



FODUS DELIVERS 802.11B/G AND 802.11B/A/G WLAN TOTAL SOLUTIONS

Fodus' B/G and B/A/G solutions satisfy all WLAN needs

Sunnyvale, Calif. and Taipei, Taiwan, Sep. 15, 2003 - Fodus, a fabless semiconductor company developing wireless broadband solutions, has taken WLAN to a new level by delivering 802.11b/g and 802.11b/a/g total solutions. Fodus' System-On-Chip (SOC) architecture reduces reliance on external components while retaining flexibility for future upgrades.

Fodus' b/g and b/a/g WLAN combo chipsets enable high-speed connections to wireless networks based on IEEE 802.11x standards at speeds up to 54Mbps and are completely compatible with existing Wi-Fi systems worldwide

Fodus' highly integrated solution also reduces component and manufacturing costs. The b/g and b/a/g chipsets both consist of two chips: a RF transceiver and a Baseband/MAC processor. Because these SOC solutions eliminate many external components such as VCOs, SRAM, or flash memory, customers will enjoy a dramatic reduction in their Bill of Materials (BOM).

Cost has always been an important consideration for electronic manufacturers, but holding down cost is projected to become even more crucial over the next few years. Ken Furer, research analyst with IDC's semiconductor group, explains: "As margins become further constricted, IDC believes this space will favor only a handful of vendors that are able to ride the cost curve by specializing in this market. Certain vendors, which can leverage lower manufacturing costs, particularly in digital and RF CMOS, should have a distinct advantage."

IDC also expects the combo approach to become predominant as assurance of backward compatibility to 802.11b and future proofing to 802.11a and 802.11g become important selection criteria.

Jeff Jan, President and CEO of Fodus Communications, agrees with IDC's assessment. "Fodus' WLAN solutions hold significant advantages for our customers in terms of cost effectiveness and upgrade flexibility," says Jan. "These chipsets are the right solutions at the right time."

In addition to providing full compatibility with present and future WLAN standards, Fodus' chipsets are compliant with Wi-Fi™ Wireless Protected Access (WPA) to ensure secure connections. Both chipsets support 64- and 128-bit Wired Equivalent Privacy (WEP), Temporal Key Integrity Protocol (TKIP), and 802.1x authentications. Fodus' integrated solutions combine the features and performance required by the WLAN market.

Availability

Fodus is currently sampling both b/g and b/a/g chipsets to select customers. PCI, CardBus, and MiniPCI

reference designs are available. End-user products will be launched in the fourth quarter.

About Fodus

Fodus Communications, founded in 2000, is a fabless semiconductor company developing highly integrated solutions for wireless broadband communications. The company develops high-performance solutions that enable wireless distribution of data, video, and voice. For more information, please visit www.fodus.com or email info@fodus.com.

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